NXP Semiconductors
Data Sheet: Technical Data

MPX2053
Rev 10, 06/2020

50 kPa on-chip temperature compensated and calibrated silicon pressure sensors

MPX2053 Series

0 to 50 kPa (0 to 7.25 psi)
40 mV Full Scale
(Typical)

The MPX2053 series devices are silicon piezoresistive pressure sensors that provide a highly accurate and linear voltage output directly proportional to the applied pressure. A single, monolithic silicon diaphragm with the strain gauge and an integrated thin-film resistor network. Precise span and offset calibration with temperature compensation are achieved by laser trimming.

Features

- Temperature compensated Over 0°C to +85°C
- Easy-to-Use chip carrier package options
- Ratiometric to supply voltage
- Gauge ported and non-ported options
- Available in easy-to-use tape and reel
- Differential and gauge pressure options

Application Examples

- Pump/Motor control
- Robotics
- Level detectors
- Medical diagnostics
- Pressure switching
- Blood pressure measurement

ORDERING INFORMATION

Device Name	Case No.	# of Ports			Pressure Type			Device Marking
		None	Single	Dual	Gauge	Differential	Absolute	
Small Outline Package (MPXV2053G Series)								
MPXV2053DP	1351			•		•		MPXV2053DP
Unibody Package (MPX2053 Series)								
MPX2053D	344	•				•		MPX2053D
MPAK Package (MPXM2053 Series)								
MPXM2053D	1320	•				•		MPXM2053D
MPXM2053DT1	1320	•				•		MPXM2053D
MPXM2053GS	1320A		•		•			MPXM2053GS
MPXM2053GST1	1320A		•		•			MPXM2053GS

UNIBODY PACKAGE

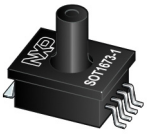
MPX2053D
CASE 344-15

SMALL OUTLINE PACKAGE

MPXV2053DP
CASE 1351-01

MPAK PACKAGES

MPXM2053D/DT1
CASE 1320-02



MPXM2053GS/GST1
CASE 1320A-02

Operating Characteristics

Table 1. Operating Characteristics (V_S = 10 V_{DC}, T_A = 25°C unless otherwise noted, P1 > P2)

Characteristic	Symbol	Min	Typ	Max	Units
Pressure Range[1]	P_{OP}	0	—	50	kPa
Supply Voltage[2]	V_S	—	10	16	V_{DC}
Supply Current	I_O	—	6.0	—	mAdc
Full Scale Span[3]	V_{FS}	38.5	40	41.5	mV
Offset[4]	—	–1.0	—	1.0	mV
Sensitivity	—	ΔV/ΔP	—	0.8	—
Linearity[5]	—	–0.6	—	0.4	$\%V_{FS}$
Pressure Hysteresis[5] (0 kPa to 50 kPa)	—	—	±0.1	—	$\%V_{FS}$
Temperature Hysteresis[5] (-40 °C to 125 °C)	—	—	±0.5	—	$\%V_{FS}$
Temperature Coefficient of Full Scale[5]	TCV_{FS}	–2.0	—	2.0	$\%V_{FS}$
Temperature Coefficient of Offset[5]	TCV_{OFF}	–1.0	—	1.0	mV
Input Impedance	Z_{IN}	1000	—	2500	Ω
Output Impedance	Z_{OUT}	1400	—	3000	Ω
Response Time[6] (10% to 90%)	t_R	—	1.0	—	ms
Warm-Up Time	—	—	20	—	ms
Offset Stability[7]	—	—	±0.5	—	$\%V_{FS}$

1. 1.0 kPa (kiloPascal) equals 0.145 psi.
2. Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.
3. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
4. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
5. Accuracy (error budget) consists of the following:
   - Linearity: Output deviation from a straight line relationship with pressure, using end point method, over the specified pressure range.
   - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
   - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25 °C.
   - TcSpan: Output deviation at full rated pressure over the temperature range of 0°C to 85 °C, relative to 25 °C.
   - TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 °C to 85 °C, relative to 25 °C.
6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
7. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

Maximum Ratings

Table 2. Maximum Ratings[1]

Rating	Max Value	Unit
Supply Voltage	16	V
Pressure (P1 > P2)	200	kPa
Storage Temperature	–40 to +125	°C
Operating Temperature Range	–40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

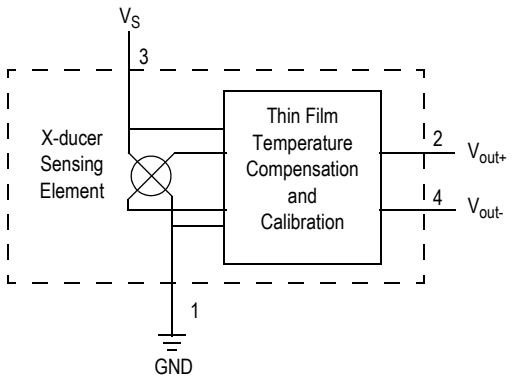


Figure 1. Temperature Compensated Pressure Sensor Schematic

Voltage Output versus Applied Differential Pressure

The differential voltage output of the sensor is directly proportional to the differential pressure applied.

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure side relative to the vacuum side. Similarly, output voltage increases as increasing vacuum is applied to the vacuum side relative to the pressure side.

On-Chip Temperature Compensation and Calibration

Figure 2 shows the minimum, maximum and typical output characteristics of the MPX2053 series at 25°C. The output is directly proportional to the differential pressure and is essentially a straight line.

A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

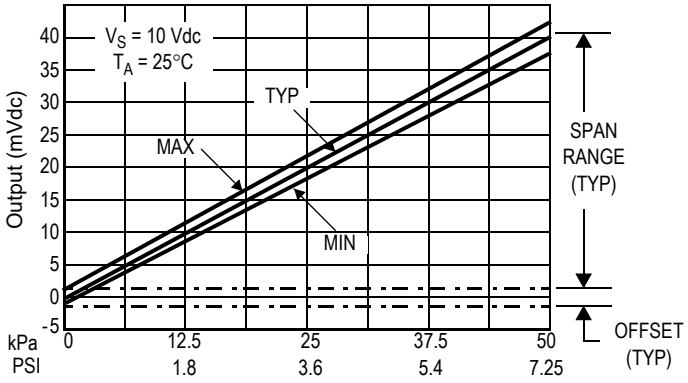


Figure 2. Output vs. Pressure Differential

LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{out} = V_{off}$ + sensitivity x P over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 3) or (2) a least squares best line fit. While a least squares fit gives the “best case” linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the “worst case” error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. The specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

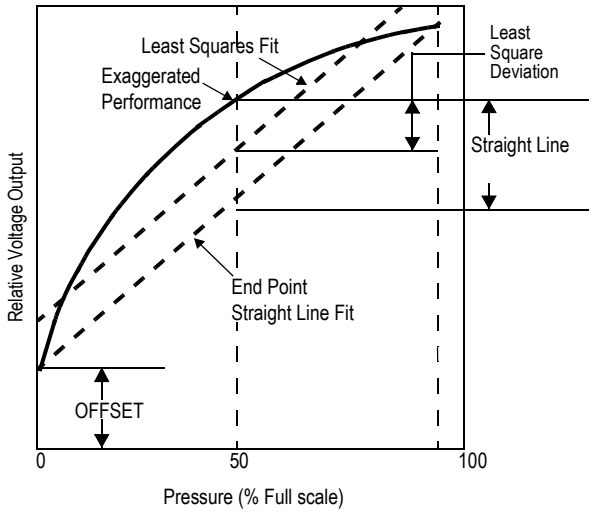


Figure 3. Linearity Specification Comparison

Figure 4 illustrates the differential or gauge configuration in the basic chip carrier (Case 344). A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

The MPX2053 series pressure sensor operating characteristics and internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long term reliability. Contact the factory for information regarding media compatibility in your application. Refer to application note AN3728, for more information regarding media compatibility.

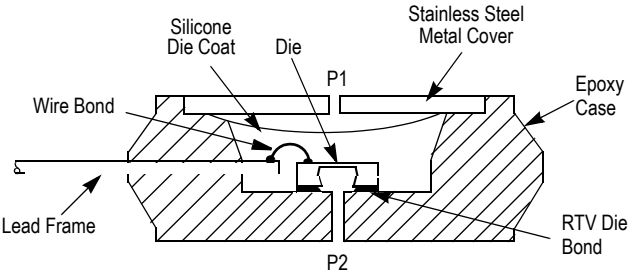
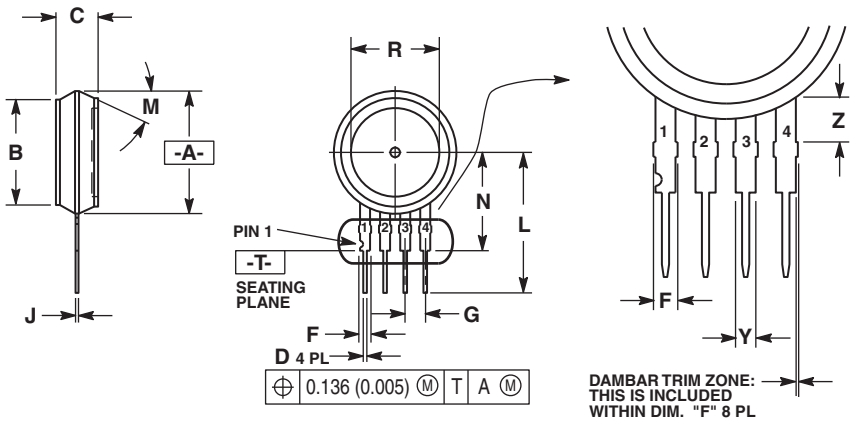


Figure 4. Unibody Package — Cross-Sectional Diagram (Not to Scale)

PACKAGE DIMENSIONS



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION -A- IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.595	0.630	15.11	16.00
B	0.514	0.534	13.06	13.56
C	0.200	0.220	5.08	5.59
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.40
L	0.695	0.725	17.65	18.42
M	30° NOM		30° NOM	
N	0.475	0.495	12.07	12.57
R	0.430	0.450	10.92	11.43
Y	0.048	0.052	1.22	1.32
Z	0.106	0.118	2.68	3.00

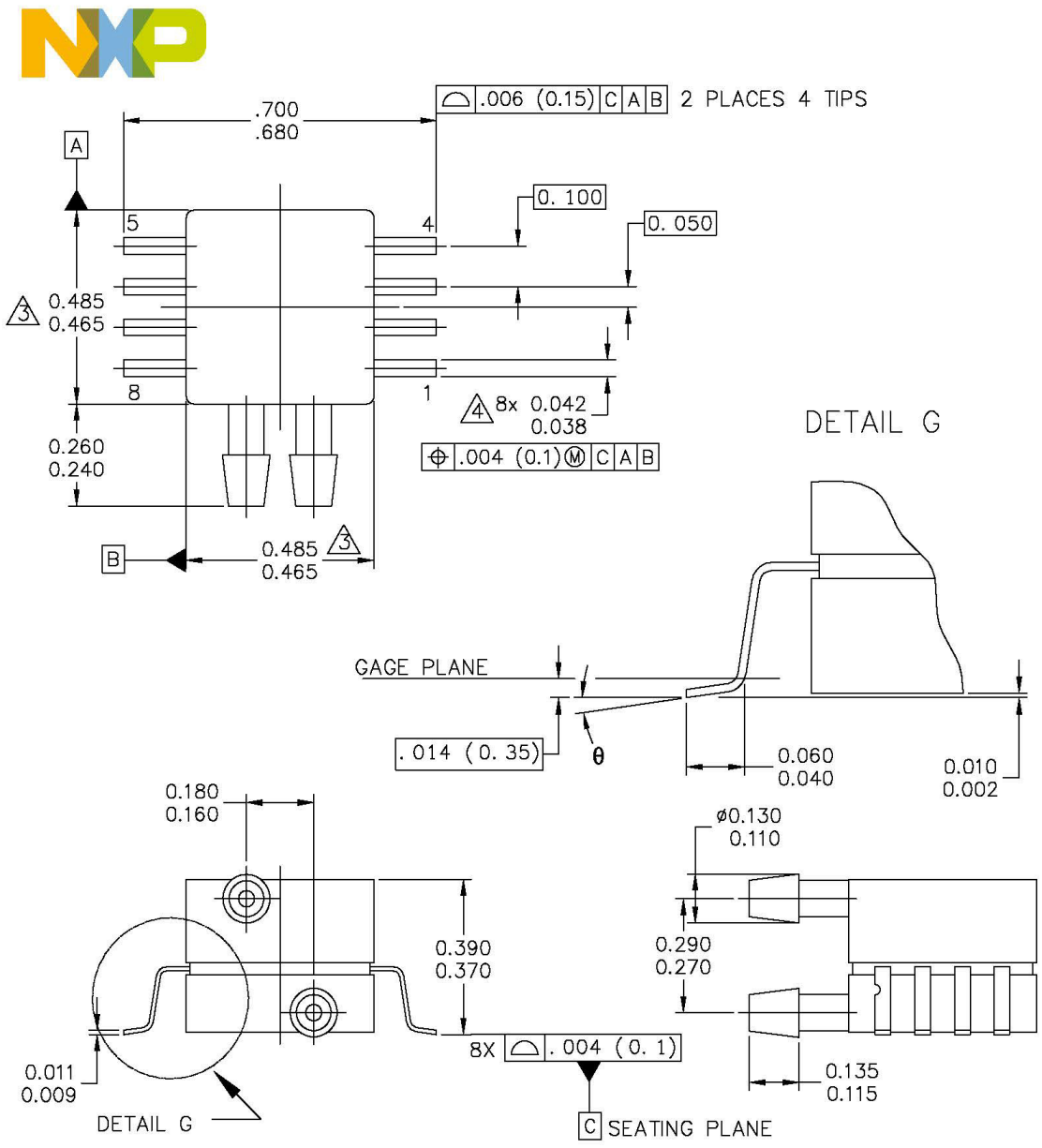
STYLE 1:
PIN 1. GROUND
2. + OUTPUT
3. + SUPPLY
4. - OUTPUT

STYLE 2:
PIN 1. V_{CC}
2. - SUPPLY
3. + SUPPLY
4. GROUND

STYLE 3:
PIN 1. GND
2. -VOUT
3. VS
4. +VOUT

CASE 344-15
ISSUE AA
UNIBODY PACKAGE

PACKAGE DIMENSIONS



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TITLE: 8 LD SNSR, DUAL PORT	DOCUMENT NO: 98ASA99255D	REV: B
	STANDARD: NON-JEDEC	
	SOT1693-1	14 MAR 2016

CASE 1351-01
ISSUE A
SMALL OUTLINE PACKAGE

PACKAGE DIMENSIONS

NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.

3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PPROTRUSIONS.
   MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.

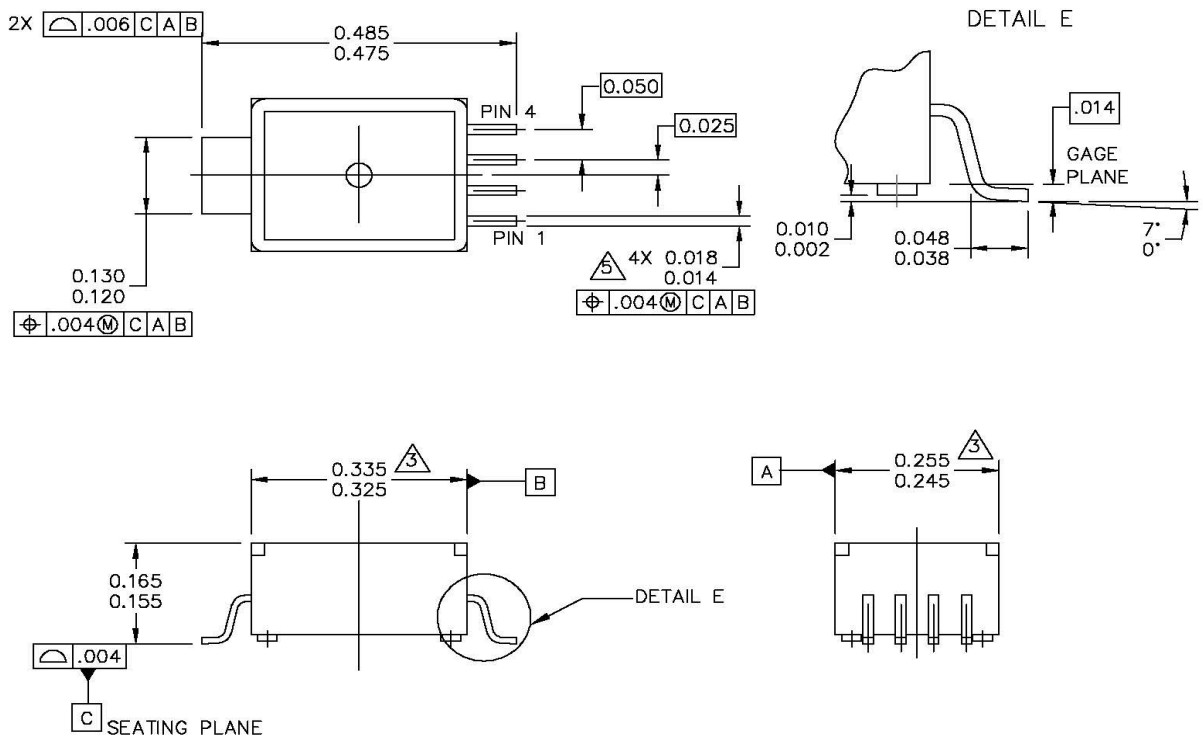
4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
   PROTRUSION SHALL BE .008 MAXIMUM.

STYLE 1:	STYLE 2:
PIN 1: GND	PIN 1: N/C
PIN 2: +Vout	PIN 2: Vs
PIN 3: Vs	PIN 3: GND
PIN 4: –Vout	PIN 4: Vout
PIN 5: N/C	PIN 5: N/C
PIN 6: N/C	PIN 6: N/C
PIN 7: N/C	PIN 7: N/C
PIN 8: N/C	PIN 8: N/C

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 8 LD SNSR, DUAL PORT	DOCUMENT NO: 98ASA99255D REV: B
	STANDARD: NON–JEDEC
	SOT1693–1 14 MAR 2016

CASE 1351-01
ISSUE A
SMALL OUTLINE PACKAGE

PACKAGE DIMENSIONS



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	STANDARD: NON-JEDEC	
	SOT1674-1	29 FEB 2016

CASE 1320-02
ISSUE B
MPAK PACKAGE

PACKAGE DIMENSIONS

NOTES:

1. DIMENSIONS ARE IN INCHES.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. DIMENSION DOES NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

PIN 1: GND
PIN 2: +Vout
PIN 3: Vs
PIN 4: –Vout

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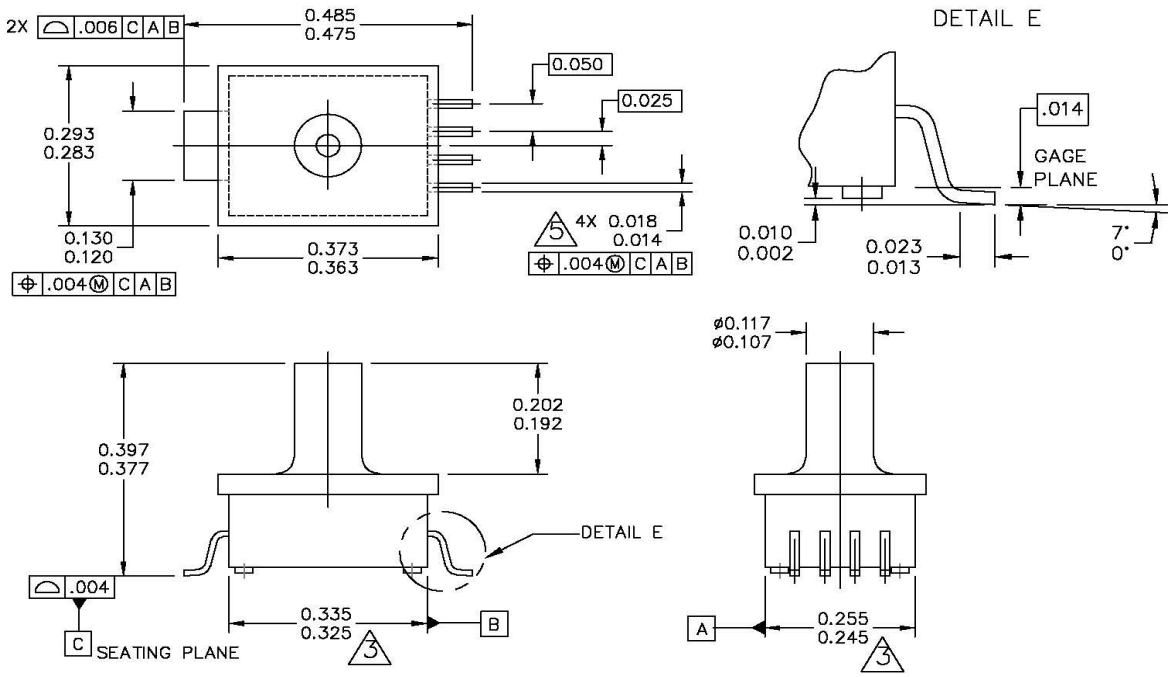
	STANDARD: NON–JEDEC	
	SOT1674–1	29 FEB 2016

CASE 1320-02
ISSUE B
MPAK PACKAGE

PACKAGE DIMENSIONS



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	SOT1673–1	29 FEB 2016

CASE 1320-02
ISSUE A
MPAK PACKAGE

PACKAGE DIMENSIONS

NOTES:

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3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
4. ALL VERTICAL SURFACES TO BE 5" MAXIMUM.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
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	STANDARD: NON–JEDEC
	SOT1673–1 29 FEB 2016

CASE 1320-02
ISSUE A
MPAK PACKAGE

Table 3. Revision History

Revision number	Revision date	Description of changes
10	06/2020	• This data sheet has been formatted to comply with the identity guidelines of NXP Semiconductors. • Ordering Information: Removed MPX2053DP, MPX2053GP and MPXV2053GP from the table. • Package images: Removed the package images for MPX2053DP, MPX2053GP and MPXV2053GP. Updated all other package images. • Operating Characteristics: Revised “Non-Linearity” to “Linearity” and added new footnote after Linearity, Pressure Hysteresis, Temperature Hysteresis, Temperature Coefficient of Full Scale, and Temperature Coefficient of Offset. • Package Dimensions: Removed package dimensions for Case 344B-01 Issue B, Unibody package, Case 344C-01 Issue B, Unibody package, and Case 1369-01, Issue D Small Outline package. Updated all other package dimension images.
9	10/2012	• Deleted references to device number MPXV2053GVP throughout the document

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MPX2053
Rev. 10
05/2020